

SELF-ALIGNING WAFER BURN-IN PROBE

ABSTRACT OF THE DISCLOSURE

The material and geometric properties of an electrical probe contact are combined to produce an electrical contact which is capable of self-alignment over many thousands of uses. The probe contact moves substantially only in a vertical direction and provides a consistent contact force with corresponding electrical contact pads on a semiconductor wafer. The probe contacts are configured in an array of a large plurality of individual contacts which extend from a base to which they are attached through apertures in an overlying mask spaced apart from the base.

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